



CALL FOR PAPERS

ICEET 2020
Apr 24-25, 2020
Istanbul, Turkey

The International Research Conference is a federated organization dedicated to bringing together a significant number of diverse scholarly events for presentation within the conference program. Events will run over a span of time during the conference depending on the number and length of the presentations.

ICEET 2020 : International Conference on Electronic Encapsulation Technologies is the premier interdisciplinary forum for the presentation of new advances and research results in the fields of Electronic Encapsulation Technologies. The conference will bring together leading academic scientists, researchers and scholars in the domain of interest from around the world. Topics of interest for submission include, but are not limited to:

Encapsulation technologies for electronic applications
Electronic packaging
Encapsulated microelectronic packages
Plastic encapsulation methods and encapsulant materials
Market conditions and manufacturers of encapsulant materials
Environmentally friendly or green encapsulants
Encapsulation process technology
Printing encapsulation technology
Characterization of encapsulant properties
Encapsulation defects and failures
Electronic equipment packaging
Advanced packaging
TSV/WAFER level packaging

Interconnection technologies
Emerging packaging technologies
Materials and substrates/leadframes
Processes and automation/equipments
Electrical modeling and simulations
Mechanical modeling and simulations
Thermal characterization and cooling solutions
Quality and reliability
Sheet metal
Cast metal
Machined metal
Molded plastic
Potting